

July 2014

# FLS3217 / FLS3247 Single-Stage PFC Primary-Side-Regulation Offline LED Driver with Integrated Power MOSFET

#### **Features**

- Cost-Effective Solution without Input Bulk Capacitor and Feedback Circuitry
- Power-Factor Correction (PFC)
- Integrated Power MOSFET
- Accurate Constant-Current (CC) Control Independent Online Voltage, Output Voltage, and Magnetizing Inductance Variation
- Linear Frequency Control for Increased Efficiency
- Open / Short-LED Protection
- Cycle-by-Cycle Current Limiting
- Over-Temperature Protection with Auto Restart
- Low Startup Current: 20µA
- Low Operating Current: 5mA
- V<sub>DD</sub> Over-Voltage Protection (OVP)
- V<sub>DD</sub> Under-Voltage Lockout (UVLO)
- Application Voltage Range: 80 V<sub>AC</sub> ~ 308 V<sub>AC</sub>

## Description

This highly integrated PWM controller with power MOSFET, FLS3217 / FLS3247, provides several features to enhance the performance of low-power flyback converters. The proprietary topology enables simplified circuit design for LED lighting applications.

By using the single-stage topology with primary-side regulation, an LED lighting board can be implemented with the few external components and minimized cost; requiring no input bulk capacitor or feedback circuitry. To implement good power factor and low THD, constant on-time control is utilized with an external capacitor connected to COMI.

Precise constant-current control regulates accurate output current versus changes in input voltage and output voltage. The operating frequency is proportionally changed by the output voltage to guarantee DCM operation with higher efficiency and simple design.

FLS3217 and FLS3247 provide protection features such as open-LED, short-LED, and over-temperature protection. The current-limit level is automatically reduced to minimize the output current and protect external components in short-LED condition.

## **Applications**

LED Lighting System

**Ordering Information** 

| Part Number | Operating<br>Temperature Range | Package                              | Packing Method |  |
|-------------|--------------------------------|--------------------------------------|----------------|--|
| FLS3217M    |                                | 7-Lead, Small Outline Package (SOIC) | Tape & Reel    |  |
| FLS3217N    | -40°C to +125°C                | 7 Load Small Outline Backage (DID)   | Tubo           |  |
| FLS3247N    |                                | 7-Lead, Small Outline Package (DIP)  | Tube           |  |

## **Application Diagram**

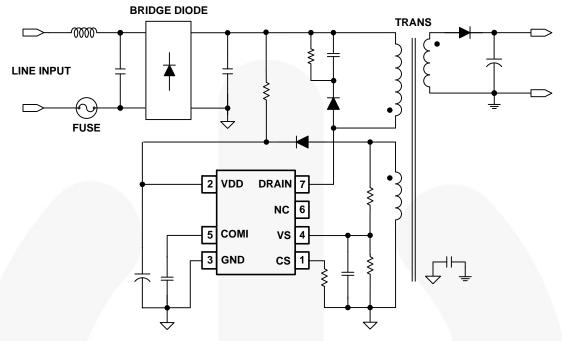


Figure 1. Typical Application

# **Internal Block Diagram**

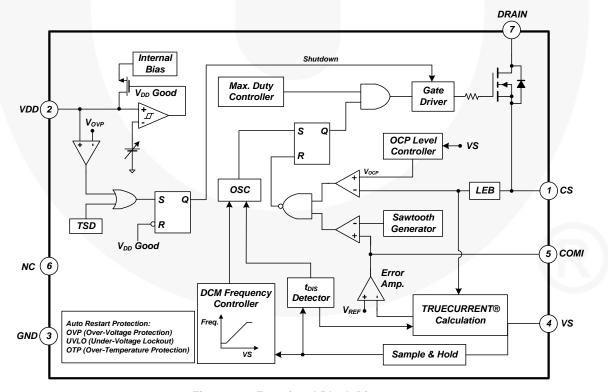
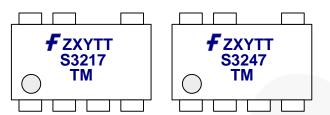


Figure 2. Functional Block Diagram

# **Marking Information**



F: Fairchild Logo

Z: Plant Code

X: 1-Digit Year Code

Y: 1-Digit Week Code

TT: 2-Digit Die Run Code

T: Package Type (M=SOIC, N=DIP)

M: Manufacture Flow Code

Figure 3. Top Mark

# **Pin Configuration**

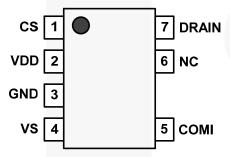


Figure 4. Pin Configuration

## **Pin Definitions**

| Pin# | Name  | Description   |  |  |  |
|------|-------|---|--|--|--|
| 1    | CS    | <b>Current Sense</b> . This pin connects a current-sense resistor to detect the MOSFET current for the output-current regulation in Constant-Current (CC) regulation.   |  |  |  |
| 2    | VDD   | Power Supply. IC operating current and MOSFET driving current are supplied using this pin.  |  |  |  |
| 3    | GND   | Ground  |  |  |  |
| 4    | VS    | Voltage Sense. This pin detects the output voltage information and discharge time for maximum frequency control and constant current regulation. This pin is connected to an auxiliary winding of the transformer via resistors of the divider. |  |  |  |
| 5    | COMI  | Constant Current Loop Compensation. This pin is connected to a capacitor between the COMI and GND pins for compensation current loop gain.  |  |  |  |
| 6    | NC    | No Connect  |  |  |  |
| 7    | DRAIN | Power MOSFET Drain. This pin is the high-voltage power MOSFET drain.  |  |  |  |

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol                           | Parameter                               | Min.                                | Max. | Unit |      |
|----------------------------------|---|-------------------------------------|------|------|------|
| $V_{VDD}$                        | DC Supply Voltage <sup>(1,2)</sup>      |                                     |      | 30   | V    |
| V <sub>VS</sub>                  | VS Pin Input Voltage                    |                                     | -0.3 | 7.0  | V    |
| V <sub>CS</sub>                  | CS Pin Input Voltage                    |                                     | -0.3 | 7.0  | V    |
| V <sub>COMI</sub>                | COMI Pin Input Voltage                  |                                     | -0.3 | 7.0  | V    |
| I <sub>D</sub>                   | Continuous Drain Current                | T <sub>A</sub> =25°C,<br>FLS3217M/N |      | 1    | A    |
|                                  |   | T <sub>A</sub> =25°C, FLS3247N      |      | 4    |      |
|                                  | Pulsed Drain Current                    | FLS3217M/N                          |      | 4    | Α    |
| I <sub>DM</sub>                  | Pulsed Drain Current                    | FLS3247N                            |      | 16   |      |
| . A                              | Avalarata Communit                      | FLS3217M/N                          | -    | 1    | ^    |
| I <sub>AR</sub>                  | Avalanche Current                       | FLS3247N                            |      | 4    | A    |
| P <sub>D</sub>                   | 5 5 1 1                                 | SOIC, T <sub>A</sub> <50°C          |      | 660  | mW   |
|                                  | Power Dissipation                       | DIP, T <sub>A</sub> <50°C           |      | 1    | W    |
| _                                |   | SOIC, T <sub>A</sub> <50°C          |      | 150  | 0000 |
| $\Theta_{JA}$                    | Thermal Resistance (Junction-to-Air)    | DIP, T <sub>A</sub> <50°C           |      | 95   | °C/W |
|                                  |   | SOIC, T <sub>A</sub> <50°C          |      | 40   |      |
| $\Theta_{\sf JC}$                | Thermal Resistance (Junction-to-Case)   | DIP, T <sub>A</sub> <50°C           |      | 25   | °C/W |
| TJ                               | Maximum Junction Temperature            |                                     | +150 | °C   |      |
| T <sub>STG</sub>                 | Storage Temperature Range               |                                     | -55  | +150 | °C   |
| $T_L$                            | Lead Temperature (Soldering 10 seconds) |                                     |      | +260 | °C   |
| FOD                              | ESD Capability, Human Body Model        |                                     |      | 5    | V    |
| ESD Capability, Charged Device M |   |                                     |      | 2    | V    |

#### Notes:

- 1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.
- 2. All voltage values, except differential voltages, are given with respect to GND pin.

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter                     | Min. | Max. | Unit |
|--------|-------------------------------|------|------|------|
| $T_A$  | Operating Ambient Temperature | -40  | 125  | °C   |

## **Electrical Characteristics**

Unless otherwise specified,  $V_{DD}$ =15 V and  $T_A$ =25°C.

| Symbol                  | Parame   | ter                            | Condition   | Min.  | Тур.  | Max.  | Unit |
|-------------------------|--|--------------------------------|---|-------|-------|-------|------|
| MOSFET Sec              | ction  |                                |   | •     |       | •     | •    |
| BV <sub>DSS</sub>       | Drain-Source Breakdown Voltage                                   |                                | I <sub>D</sub> =250 μA, V <sub>GS</sub> =0 V                          | 700   |       |       | V    |
|                         |  | FLS3217M                       | 1 05 1 1/ 101/  |       | 13    | 16    | Ω    |
| $R_{DS(ON)}$            | Static Drain-Source On Resistance                                | FLS3217N                       | I <sub>D</sub> =0.5 A, V <sub>GS</sub> =10 V                          |       | 8.8   | 11.0  | Ω    |
|                         | On reductance  | FLS3247N                       | I <sub>D</sub> =1 A, V <sub>GS</sub> =10 V                            |       | 2.4   | 2.8   | Ω    |
|                         |  | FLS3217M                       | ., .,,,,  |       | 175   | 200   | pF   |
| $C_{ISS}$               | Input Capacitance  | FLS3217N                       | V <sub>GS</sub> =0 V, V <sub>DS</sub> =25 V,<br>f <sub>S</sub> =1 MHz |       | 250   |       | pF   |
|                         |  | FLS3247N                       |   |       | 435   |       | pF   |
|                         |  | FLS3217M                       | ., ., ., .  |       | 23    | 25    | pF   |
| Coss                    | Output Capacitance   | FLS3217N                       | $V_{GS}$ =0V, $V_{DS}$ =25V, $I_{S}$ =1MHz                            |       | 25    |       | pF   |
|                         |  | FLS3247N                       | 13 11112  |       | 51    |       | pF   |
| V <sub>DD</sub> Section |  |                                |   |       |       |       |      |
| $V_{\text{DD-ON}}$      | Turn-On Threshold \  | /oltage                        |   | 14.5  | 16.0  | 17.5  | V    |
| V <sub>DD-OFF</sub>     | Turn-Off Threshold \   | /oltage                        |   | 6.75  | 7.75  | 8.75  | V    |
| I <sub>DD-OP</sub>      | Operating Current  |                                | V <sub>S</sub> =2.4 V, C <sub>L</sub> =MOSFET C <sub>ISS</sub>        | 2.85  | 4.00  | 5.00  | mA   |
| I <sub>DD-ST</sub>      | Startup Current  |                                | V <sub>DD</sub> =V <sub>DD-ON</sub> – 0.16 V                          |       | 2     | 20    | μA   |
| V <sub>OVP</sub>        | V <sub>DD</sub> Over-Voltage Protection Level                    |                                |   | 22.0  | 23.5  | 25.0  | V    |
| Oscillator Se           | ection   |                                |   |       |       |       |      |
| f <sub>MAX-CC</sub>     | Maximum Frequency  | / in CC                        | V <sub>DD</sub> =10 V, 20 V   | 60    | 65    | 70    | kHz  |
| f <sub>MIN-CC</sub>     | Minimum Frequency in CC  |                                | V <sub>DD</sub> =10 V, 20 V   | 21.0  | 23.5  | 26.0  | kHz  |
| VS <sub>MAX-CC</sub>    | VS for Maximum Frequency in CC                                   |                                | Frequency=Maximum<br>Frequency-2 kHz                                  | 2.25  | 2.35  | 2.45  | V    |
| VS <sub>MIN-CC</sub>    | VS for Minimum Fred  | VS for Minimum Frequency in CC |   | 0.55  | 0.85  | 1.15  | V    |
| t <sub>ON(MAX)</sub>    | Maximum Turn-on T  | ime                            |   | 12    | 14    | 16    | μs   |
| Current-Sens            | se Section   |                                |   |       |       |       |      |
| $V_{RV}$                | Reference Voltage  |                                |   | 2.475 | 2.500 | 2.525 | V    |
| V <sub>CCR</sub>        | Variation Test Voltage on CS Pin for Constant Current Regulation |                                | V <sub>CS</sub> =0.24 V   | 2.38  | 2.43  | 2.48  | V    |
| t <sub>LEB</sub>        | Leading-Edge Blanking Time                                       |                                |   |       | 300   | /     | ns   |
| t <sub>MIN</sub>        | Minimum On Time in CC  |                                | V <sub>VS</sub> =-0.5 V, V <sub>CS</sub> =1.5 V                       |       | 600   |       | ns   |
| t <sub>PD</sub>         | Propagation Delay to GATE<br>Output                              |                                |   | 50    | 100   | 150   | ns   |
| D <sub>SAW</sub>        | Duty Cycle of SAW Limiter  |                                |   |       | 40    |       | %    |
| t <sub>DIS-BNK</sub>    | t <sub>DIS</sub> Blanking Time of VS                             |                                |   |       | 1.5   |       | μs   |
| I <sub>VS-BNK</sub>     | VS Current for VS BI   | anking                         |   |       | 100   |       | μA   |

Continued on the following page...

# **Electrical Characteristics** (Continued)

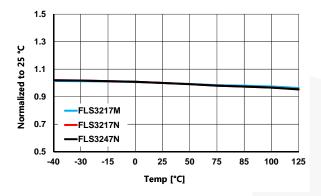
Unless otherwise specified,  $V_{DD}$ =15 V and  $T_A$ =25°C.

| Symbol                              | Parameter                                     | Condition                                     | Min. | Тур. | Max. | Unit |  |  |
|-------------------------------------|---|---|------|------|------|------|--|--|
| Current-Erre                        | Current-Error-Amplifier Section               |   |      |      |      |      |  |  |
| Gm                                  | Transconductance                              |   |      | 85   |      | μmho |  |  |
| I <sub>COMI-SINK</sub>              | COMI Sink Current                             | V <sub>EAI</sub> =3 V, V <sub>COMI</sub> =5 V | 25   |      | 38   | μΑ   |  |  |
| I <sub>COMI-SOURCE</sub>            | COMI Source Current                           | V <sub>EAI</sub> =2 V, V <sub>COMI</sub> =0 V | 25   |      | 38   | μА   |  |  |
| V <sub>COMI-HGH</sub>               | COMI High Voltage                             | V <sub>EAI</sub> =2 V                         | 4.7  |      |      | V    |  |  |
| V <sub>COMI-LOW</sub>               | COMI Low Voltage                              | V <sub>EAI</sub> =3 V                         |      |      | 0.1  | V    |  |  |
| Over-Currer                         | nt Protection Section                         |   |      |      |      |      |  |  |
| V <sub>OCP</sub>                    | V <sub>CS</sub> Threshold Voltage for OCP     | 0.60  | 0.67 | 0.74 | V    |      |  |  |
| V <sub>LowOCP</sub>                 | V <sub>CS</sub> Threshold Voltage for Low OCP |   | 0.13 | 0.18 | 0.23 | V    |  |  |
| V <sub>LowOCP-EN</sub>              | VS Threshold Voltage to Enable L              |   | 0.40 |      | V    |      |  |  |
| V <sub>LowOCP-DIS</sub>             | VS Threshold Voltage to Disable               |   | 0.60 |      | V    |      |  |  |
| Over-Temperature-Protection Section |   |   |      |      |      |      |  |  |
| T <sub>OTP</sub>                    | Threshold Temperature for OTP <sup>(3)</sup>  |   | 140  | 150  | 160  | °C   |  |  |
| T <sub>OTP-HYS</sub>                | Restart Junction Temperature Hys              |   | 10   |      | °C   |      |  |  |

#### Note:

3. When the over-temperature protection (OTP) is activated, the power system enters Auto-Recovery Mode and output is disabled.

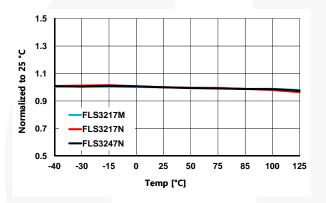
# **Typical Performance Characteristics**



1.5 Normalized to 25 1.1 0.9 FLS3217M 0.7 FLS3217N FLS3247N 0.5 -30 -40 -15 25 50 75 85 100 Temp [°C]

Figure 5.  $V_{DD-ON}$  vs. Temperature

Figure 6. V<sub>DD-OFF</sub> vs. Temperature



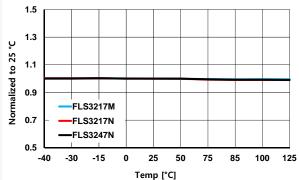
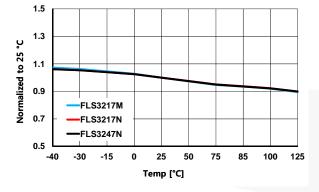


Figure 7. IDD-OP vs. Temperature

Figure 8. V<sub>OVP</sub> vs. Temperature



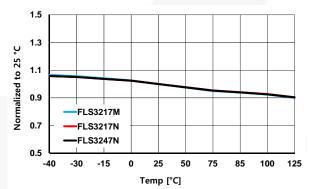
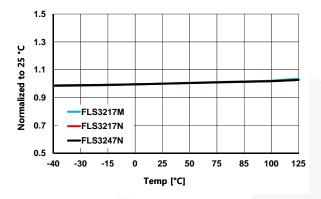


Figure 9. f<sub>MAX\_CC</sub> vs. Temperature

Figure 10.  $f_{MIN\_CC}$  vs. Temperature

# Typical Performance Characteristics (Continued)



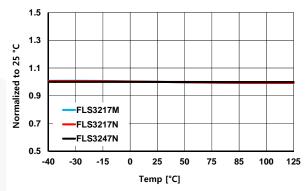


Figure 11. V<sub>CCR</sub> vs. Temperature

Figure 12. V<sub>VVR</sub> vs. Temperature

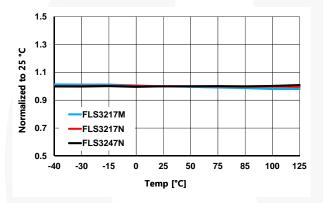


Figure 13. V<sub>OCP</sub> vs. Temperature

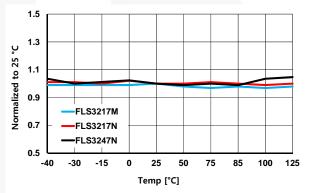


Figure 14. V<sub>OCP\_Low</sub> vs. Temperature

## **Functional Description**

FLS3217 / FLS3247 is an AC-DC PWM controller for LED lighting applications. TRUECURRENT® techniques regulate accurate LED current independent of input voltage, output voltage, and magnetizing inductance variations. The linear frequency control in the oscillator reduces conduction loss and maintains DCM operation in the wide range of output voltage, which implements high power factor correction in a single-stage flyback topology. A variety of protections, such as short/open-LED protection, over-temperature protection, and cycle-by-cycle current limitation stabilize system operation and protect external components.

#### Startup

Powering at startup is slow due to the low feedback-loop bandwidth in the PFC converter. To increase power during startup, the internal oscillator counts 12ms to define Startup Mode. During Startup Mode, turn-on time is determined by current-mode control with 0.2V voltage limit. Transconductance becomes 14 times bigger, as shown in Figure 15. After Startup Mode, turn-on time is controlled by Voltage Mode, using the COMI voltage. The error amplifier transconductance is reduced to 85µmho.

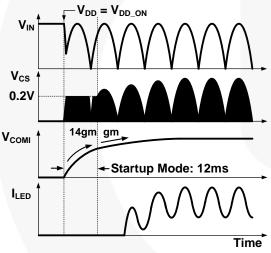


Figure 15. Startup Sequence

#### **Constant Current Regulation**

The output current can be estimated using the peak drain current and inductor current discharge time because output current is same as the average of the diode current in steady state. The peak value of the drain current is determined by the CS pin and the inductor discharge time ( $t_{\rm DIS}$ ) is sensed by  $t_{\rm DIS}$  detector. By using three pieces of information (peak drain current, inductor discharging time, and operating switching period); the TRUECURRENT block calculates estimates the output current. The output of the TRUECURRENT calculation is compared with an internal precise reference to generate an error voltage,  $V_{\rm COMI}$ , which determines the turn-on time in Voltage-Mode control. With Fairchild's innovative technique, constant current output can be precisely controlled.

# Power-Factor Controller (PFC) and Total Harmonic Distortion (THD)

In a conventional boost converter, Boundary Conduction Mode (BCM) is generally used to keep input current in phase with input voltage for Power Factor (PF) and Total Harmonic Distortion (THD). In flyback / buck boost topology, constant turn-on time and constant frequency I Discontinuous Conduction Mode (DCM) can implement high PF and low THD as shown in Figure 16. Constant turn-on time is maintained by the internal error amplifier and a large external capacitor (typically over  $1\mu F$ ) at the COMI pin. Constant frequency and DCM operation is managed by linear frequency control.

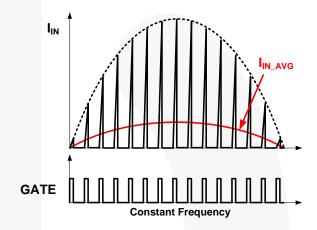


Figure 16. Input Current and Switching

#### **Linear Frequency Control**

DCM should be guaranteed for high power factor in flyback topology. To maintain DCM in the wide range of output voltage, frequency is linearly changed by output voltage in linear frequency control. Output voltage is detected by auxiliary winding and a resistive divider connected to the VS pin, as shown in Figure 17.

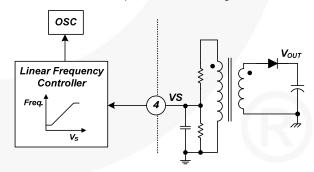


Figure 17. Linear Frequency Control

When the output voltage decreases, the secondary diode conduction time is increased and the linear frequency control lengthens the switching period. This maintains DCM operation in the wide output voltage range, as shown in Figure 18. The frequency control also lowers primary rms current with better power efficiency in full-load condition.

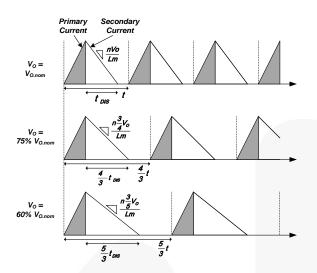


Figure 18. Primary and Secondary Current

#### **BCM Control**

The end of secondary diode conduction time is possibly over a switching period set by linear frequency control. In this case, FLS3217 and FLS3247 don't allow CCM and the operation mode changes from DCM to BCM. Therefore, FLS3217 and FLS3247 eliminate subharmonic distortion in CCM.

#### **Short-LED Protection**

In the event of a short LED condition, the switching MOSFET and secondary diode are usually stressed by the high-power current. However, FLS3217 and FLS3247 change OCP level in short-LED condition. When  $\mathsf{V}_S$  is lower than 0.4 V, the OCP level lowers to 0.2 V from 0.7 V, as shown in Figure 17. Power is limited and external component current stress is relieved.

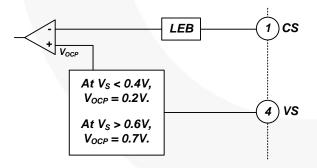


Figure 19. Internal OCP Block

Figure 20 shows operational waveforms at short-LED condition. Output voltage is quickly lowered to 0V after the LED-short event. Then the reflected auxiliary voltage is also 0V, making  $V_S$  less than 0.4 V. 0.2 V OCP level limits the primary-side current and  $V_{DD}$  "hiccups" up and down in between UVLO hysteresis.

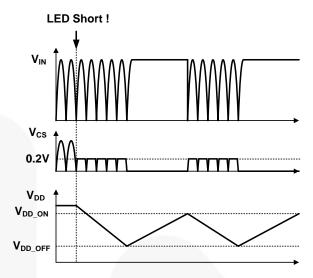


Figure 20. Waveforms at Short-LED Condition

#### Open LED Protection

FLS3217 and FLS3247 protect external components, such as diode and capacitor, at secondary side in open-LED condition. During switch-off, the  $V_{\rm DD}$  capacitor is charged up to the auxiliary winding voltage, which is applied as the reflected output voltage. Because the  $V_{\rm DD}$  voltage has output voltage information, the internal voltage comparator on the VDD pin can trigger output over-voltage protection (OVP), as shown in Figure 21. When at least one LED is open-circuited, output load impedance becomes very high and the output capacitor is quickly charged up to  $V_{\rm OVP}$  x Ns / Na. Then switching is shutdown and  $V_{\rm DD}$  block goes into "Hiccup Mode" until the open-LED condition is removed, shown in Figure 22.

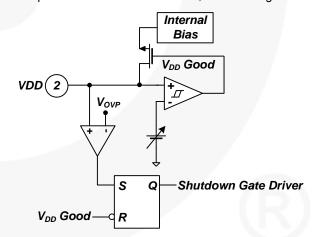


Figure 21. Internal OVP Block

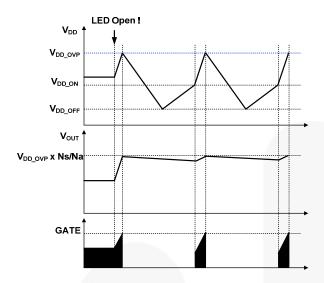


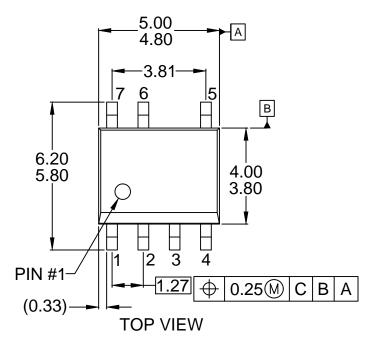
Figure 22. Waveforms at Open-LED Condition

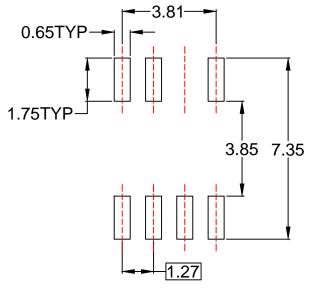
## **Under-Voltage Lockout (UVLO)**

The turn-on and turn-off thresholds are fixed internally at 16 V and 7.5 V, respectively. During startup, the VDD capacitor must be charged to 16 V through the startup resistor, so that the FLS32x7 is enabled. The VDD capacitor supplies VDD until power can be delivered from the auxiliary winding of the main transformer. VDD must not drop below 7.5 V during startup. The UVLO hysteresis window ensures that the VDD capacitor is adequate to supply VDD during startup.

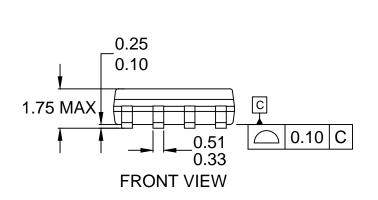
## **Over-Temperature Protection (OTP)**

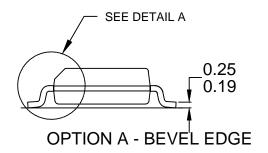
The built-in temperature-sensing circuit shuts down PWM output once the junction temperature exceeds 150°C. While PWM output is off, VDD gradually drops to the UVLO voltage. Some of the internal circuits are shut down and VDD gradually increases again. When VDD reaches 16 V, all the internal circuits start operating. If the junction temperature is still higher than 140°C, the PWM controller shuts down immediately.

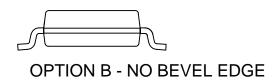


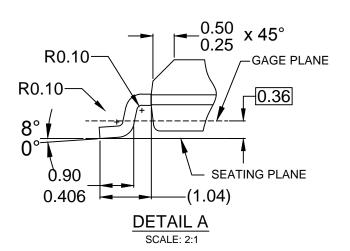


LAND PATTERN RECOMMENDATION



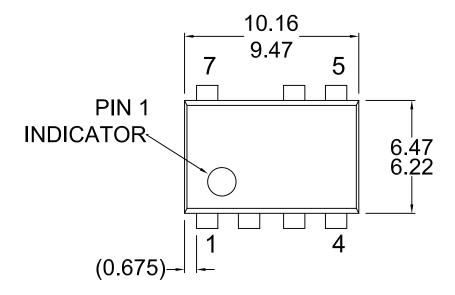


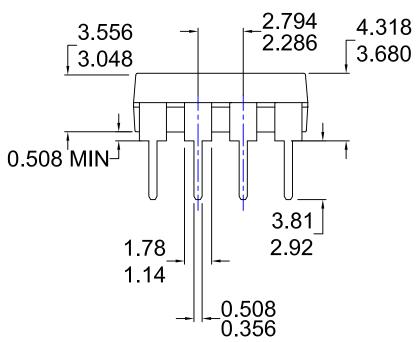


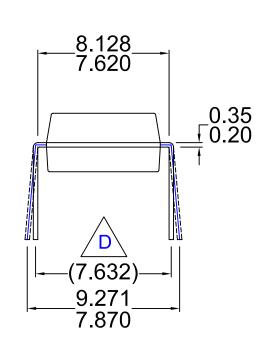


## NOTES:

- A) THIS PACKAGE DOES NOT FULLY CONFORMS TO JEDEC MS-012 VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) DRAWING FILENAME: M07Brev3







# **NOTES:**

- A) THIS PACKAGE CONFORMS TO JEDEC MS-001 VARIATION AA EXCEPT LEAD COUNT.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
  D) DIMENSION WITH TERMINALS CONSTRAINED

PERPENDICULAR TO PRINTED CIRCUIT BOARD.

E) DRAWING FILE NAME: MKT-NA07CREV1





#### TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

 $\begin{array}{lll} {\sf AccuPower^{TM}} & & {\sf F-PFS^{TM}} \\ {\sf Awinda}^{\otimes} & {\sf FRFET}^{\otimes} \\ {\sf AX-CAP}^{\otimes*} & & {\sf Global\ Power\ Resource}^{\sf SM} \end{array}$ 

BitSiC™ GreenBridge™
Build it Now™ Green FPS™

CorePLUS™ Green FPS™ e-Series™

Current Transfer Logic™ ISOPLANAR™

DEUXPEED® Making Small Speakers Sound Louder

 Dual Cool™
 and Better™

 EcoSPARK®
 MegaBuck™

 EfficientMax™
 MICROCOUPLER™

ESBC™

MicroFET™

MicroPak™

MicroPak™

MicroPak2™

Fairchild®

Fairchild Semiconductor®

FACT Quiet Series™

MotionMax™

MotionGrid®

MotionGrid®

PowerTrench<sup>®</sup> PowerXS™

Programmable Active Droop™

QFET<sup>®</sup> QS™

> Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™

SYSTEM SERVERAL®\*

TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect

TriFault Detect™
TRUECURRENT®\*
µSerDes™

SerDes"
UHC®
Ultra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XST™
XSEMS™
从童™

\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT <a href="http://www.fairchildsemi.com">http://www.fairchildsemi.com</a>. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

#### As used herein:

- Life support devices or systems are devices or systems which, (a) are
  intended for surgical implant into the body or (b) support or sustain
  life, and (c) whose failure to perform when properly used in
  accordance with instructions for use provided in the labeling, can be
  reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

| Definition of Terms      |                       |   |
|--------------------------|-----------------------|---|
| Datasheet Identification |                       | Definition  |
| Advance Information      | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
| Preliminary              | First Production      | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production       | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.   |
| Obsolete                 | Not In Production     | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.  |

Rev. 171